

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT4768301

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
RUNG-DE WANG	12/05/2017
CHEN-HSUN LIU	12/05/2017
CHIN-YU KU	12/05/2017
TE-HSUN PANG	12/05/2017
CHIA-HUA WANG	12/05/2017
PEI-SHING TSAI	12/05/2017
PO-CHANG LIN	12/05/2017
RECEIVING PARTY DATA	
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.
Street Address:	NO.8, LI-HSIN RD. 6, HSINCHU SCIENCE PARK,
City:	HSINCHU
State/Country:	TAIWAN
Postal Code:	300-78
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15866472
CORRESPONDENCE DATA	
Fax Number:	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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ATTORNEY DOCKET NUMBER:	71619-US-PA
NAME OF SUBMITTER:	BELINDA LEE
SIGNATURE:	/Belinda Lee/
DATE SIGNED:	01/10/2018
Total Attachments: 4	

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**DECLARATION AND ASSIGNMENT
FOR UTILITY OR DESIGN PATENT APPLICATION**

Declaration Submitted With Initial Filing

OR

Declaration Submitted After Initial Filing (surcharge 37 CFR 1.16(f) required)

(Title of the Invention)

**SEMICONDUCTOR STRUCTURE AND MANUFACTURING METHOD
THEREOF**

As a below named inventor (hereinafter designated as the undersigned), I hereby declare that:

This declaration is directed to:

The attached application,

OR

United States Application Number or PCT International application number

_____ Filed on _____

The above-identified application was made or authorized to be made by me.

I believe I am the original inventor or an original joint inventor of a claimed invention in the application.

The undersigned hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

**DECLARATION AND ASSIGNMENT
FOR UTILITY OR DESIGN PATENT APPLICATION**

WHEREAS, the undersigned has invented certain new and useful improvements described in the application identified.

WHEREAS 1. Taiwan Semiconductor Manufacturing Co., Ltd.
of No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78,
R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring the undersigned's interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by the undersigned, the undersigned has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said rights, title and interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said the undersigned had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

The undersigned further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

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DECLARATION AND ASSIGNMENT
FOR UTILITY OR DESIGN PATENT APPLICATION

Signature: Rung-De Wang Date: 2017.12.05
Legal Name of Sole or First Inventor: Rung-De Wang
Residence: Kaohsiung City, Taiwan
Mailing Address: c/o No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.

Signature: Chen-Hsun Liu Date: 2017.12.05
Legal Name of Additional Joint Inventor, if any: Chen-Hsun Liu
Residence: Tainan City, Taiwan
Mailing Address: c/o No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.

Signature: [Signature] Date: Dec 5, 2017.
Legal Name of Additional Joint Inventor, if any: Chin-Yu Ku
Residence: Hsinchu City, Taiwan
Mailing Address: c/o No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.

Signature: Te-Hsun Pang Date: Dec. 5, 2017
Legal Name of Additional Joint Inventor, if any: Te-Hsun Pang
Residence: Tainan City, Taiwan
Mailing Address: No.8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, R.O.C.

Signature: Chia-Hua Wang Date: Dec. 5, 2017
Legal Name of Additional Joint Inventor, if any: Chia-Hua Wang
Residence: Tainan City, Taiwan
Mailing Address: c/o No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.

Signature: Pei-Shing Tsai Date: 2017/12/5
Legal Name of Additional Joint Inventor, if any: Pei-Shing Tsai
Residence: Tainan City, Taiwan
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DECLARATION AND ASSIGNMENT
FOR UTILITY OR DESIGN PATENT APPLICATION

Signature: Po-Chang Lin Date: 2019/12/05

Legal Name of Additional Joint Inventor, if any: Po-Chang Lin

Residence: Kaohsiung City, Taiwan

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